

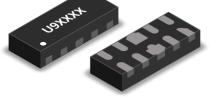






4-CHANNEL A TVS ARRAY

TVS ARRAY ▲ SMD type ESD Protection for high-speed data lines Protects four I/O lines Ultra-low capacitance (I/O) to GND ▲ 0.45pF 2.5mm x 1.0mm x 0.5mm ▲ DFN2510-10L package AEC-Q101 qualified







SPECIFICATION

Item		Characteristics
Operating Junction Temperature Range	Tı	-55°C to +125°C
Storage Temperature Range	Ts	-55°C to +150°C
Peak Pulse Current (8/20μs)	I _{PP}	5A
ESD Rating (Per IEC 61000-4-2 ▲ Contact)	V _{ESD}	±15kV
ESD Rating (Per IEC 61000-4-2 ▲ Air)	V _{ESD}	±15kV

DESCRIPTION

The UT8413A is a high-performance transient voltage suppressor (TVS) array designed to protect four channel 3.3V high speed data lines from Electrostatic Discharge (ESD), Cable Discharge Event (CDE), and Electrical Fast Transient (EFT).

This TVS array features ultra-low capacitance and low ESD clamping voltage using iPU's proprietary deep snapback technology.

The small flow-through style package enables simple PCB layout and facilitates necessary matched trace lengths to maintain consistent impedance between high-speed differential lines such as USB 3.0, HDMI 1.3/1.4, DisplayPort[™] and eSATA interfaces.

EMC STANDARDS

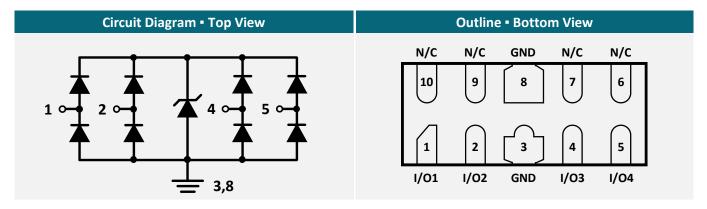
IEC 61000-4-2 (ESD): ±15kV (Contact) IEC 61000-4-2 (ESD): ±15kV (Air) IEC 61000-4-4 (EFT): 50A (5/50ns) IEC 61000-4-5 (Lightning): 5A (8/20μs)

APPLICATIONS

Automotive	Display Port	Data and I/O	SATA/eSATA	Thunderbolt	USB 2.0, 3.0
	Interface	Lines Protection	Interface	Interface	and 3.1
				3	P



PIN DESCRIPTION



ELECTRICAL CHARACTERISTICS A T_J = 25°C, unless otherwise noted

Item	Condition	Symbol	Min.	Тур.	Max.	Unit
Reverse Working Voltage	Any I/O Pin to GND	V_{RWM}			3.3	V
Breakdown Voltage	I_{BR} = 1mA, any I/O Pin to GND	V_{BR}	5	6.5	8.5	V
Forward Voltage	$I_F = 15$ mA, any I/O Pin to GND	V_{F}		1		V
Reverse Leakage Current	V_{RWM} = 3.3V, any I/O Pin to GND	I_R			1	μΑ
Surge Clamping Voltage (8/20µs)	I _{PP} = 5A, any I/O Pin to GND	V_{C}		6.2	7	V
TLP Clamping Voltage Note1	I_{TLP} = 1A, any I/O Pin to GND	V_{C}		5.3		V
TLP Clamping Voltage Note1	$I_{TLP} = 16A$, any I/O Pin to GND	V_{C}		9		V
TLP Dynamic Resistance Note2	Any I/O Pin to GND	R_{DYN}		0.25		Ω
	$V_R = 0V$, $f = 1MHz$, any I/O Pin to GND			0.45	0.6	
Junction Capacitance	$V_R = 1.65V$, $f = 1MHz$, any I/O Pin to GND	6		0.44	0.6	5
	$V_R = 0V$, $f = 1MHz$, between I/O Pins			0.05	0.06	pF
	$V_R = 1.65V$, $f = 1MHz$, between I/O Pins			0.05	0.06	

Note

t_{period} = 100ns, t_r = 1ns
t_{period} = 100ns, t_r = 1ns



TYPICAL OPERATING CHARACTERISTICS

Fig. 1 - Junction Capacitance (I/O Pin to GND)

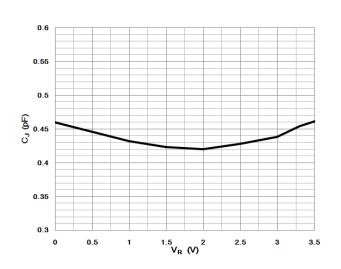


Fig. 2 • TLP Clamping Voltage (tperiod = 100ns, tr = 1ns)

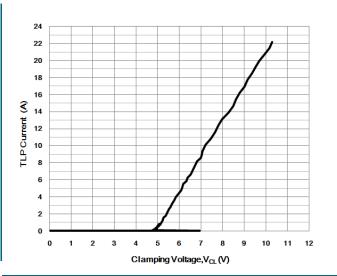


Fig. 3 - Junction Capacitance (I/O Pin to I/O Pin)

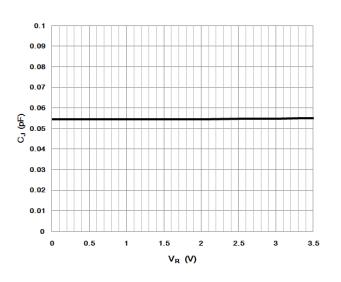
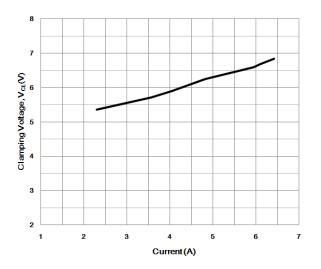
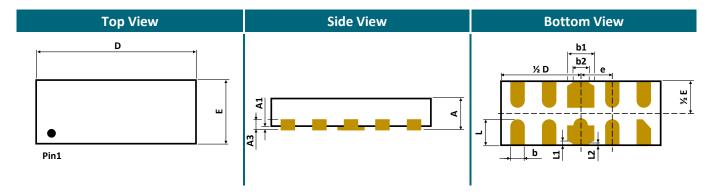


Fig. 4 - Positive Surge Clamping Voltage (8/20μs)





PACKAGE OUTLINE AND PART MARKING



Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)	
Α	0.40	0.50	0.60	
A1	0.00	0.02	0.05	
А3		0.152 REF		
b	0.15	0.20	0.25	
b1	0.35		0.45	
b2	0.13		0.30	
D	2.40	2.50	2.60	
Е	0.90	1.00	1.10	
е		0.50 BSC		
L1	0.075 REF			
L2		0.050 REF		
L	0.30	0.40	0.50	



Marking:

U9: Product code

UT8413A

XXXX: Date code

Note

1: Package Outline Unit Description:

BSC: Basic. Represents theoretical exact dimension or dimension target.

MIN: Minimum dimension specified

MAX: Maximum dimension specified

REF: Reference. Represents dimension for reference use only. This value is not a device specification.

TYP: Typical. Provided as a general value. This value is not a device specification.

2: Dimensions in Millimeters

3: Drawing not to scale

4: These dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm.

ORDERING INFORMATION

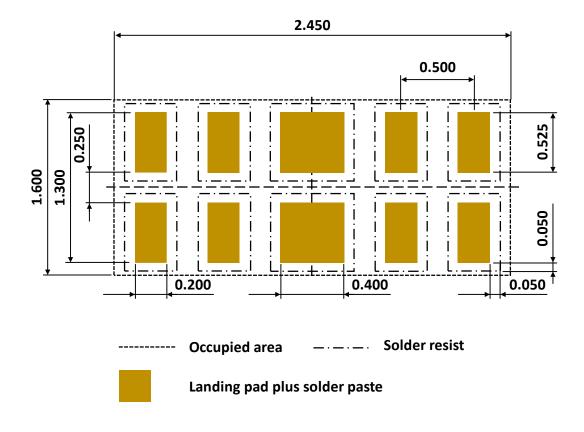
Part Number	Package Type	Package Code	Part Marking	Parameter
UT8413AD5A	DFN2510-10L	D5A	U9XXXX	U9 = Product Code XXXX = Date Code

Package Type	Vacuum Package				
DENI2510 101	Packing	Reel 180mm (7")	Inner Box (3 Reels)	Carton (12 Boxes)	
DFN2510-10L	Tape and Reel	3 000pcs	9 000pcs	108 000pcs	

MGT ▲ Manufacturer Group of Technology



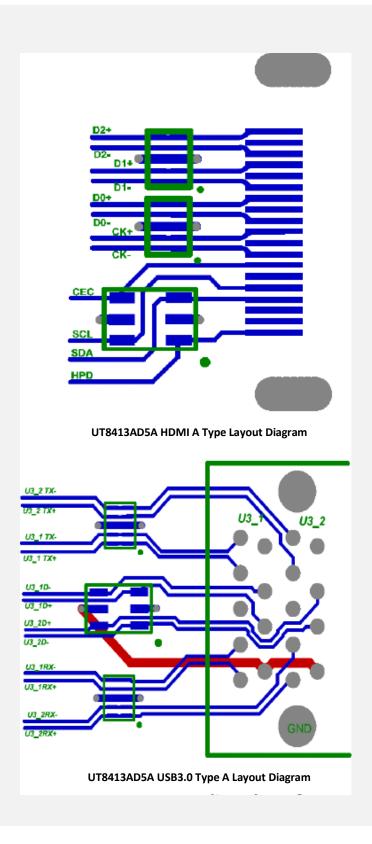
RECOMMENDED PAD LAYOUT FOR DFN2510-10L ▲ All dimensions in mm





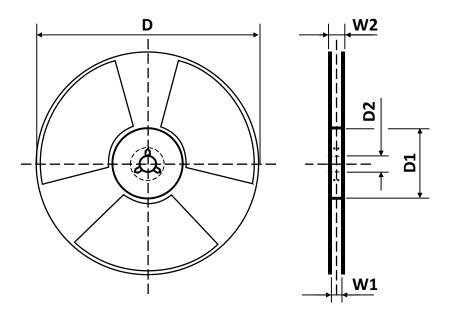
TYPICAL APPLICATION CIRCUIT

Fig. 5 • USB HDMI A Type and USB 3.0 Type A Protection



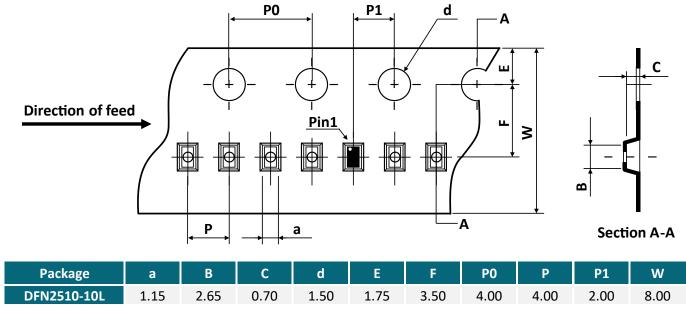


REEL DIMENSIONS ▲ All dimensions in mm



Tape Size	Reel Size	D	D1	D2	W1	W2
8mm	7 inch	Ø178.00	54.40	13.00	9.50	12.30

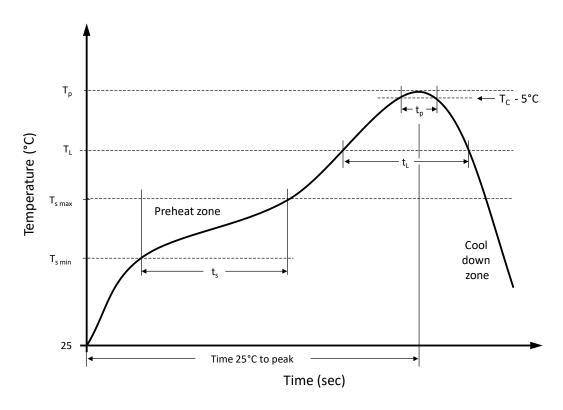
TAPE DIMENSIONS ▲ All dimensions in mm



Note: All dimensions meet EIA-481-D requirements.



RECOMMENDED REFLOW SOLDERING PROFILE



Recommended reflow soldering conditions ▲ **Refer to JEDEC J-STD-020E**

Profile Features		Sn-Pb Eutetic Assembly	Pb-Free Assembly
Preheat temperature min.	$T_{s min}$	100 °C	150 °C
Preheat temperature max.	T _{s max}	150 °C	200 °C
Preheat time t _s from T _{s min} to T _{s max}	ts	120 seconds	120 seconds
Ramp-up rate (T₁ to Tp)		max. 3 °C/second	max. 3 °C/second
Liquidous temperature	T_L	183 °C	217 °C
Time t _L maintained above T _L	t _L	150 seconds max.	150 seconds max.
Peak package body temperature	Tp	235°C	260°C
Timeframe of within 5°C below and up to max actual peak body temperature	t _p	20 seconds max.	30 seconds max.
Ramp-down rate (T _L to T _p)		max. 6 °C/second	max. 6 °C/second
Time 25°C to peak temperature		max. 6 minutes	max. 8 minutes



REVISION TABLE

Revision	Date	Status	Notes
001	01/10/2021	Initial release	Initial publication

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